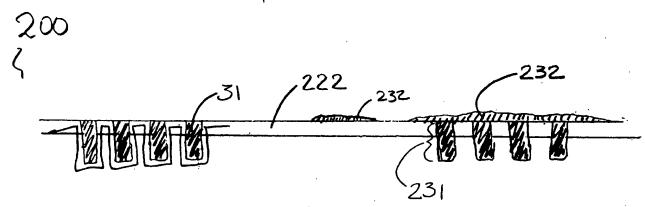
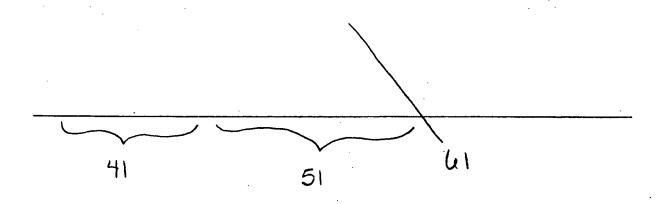


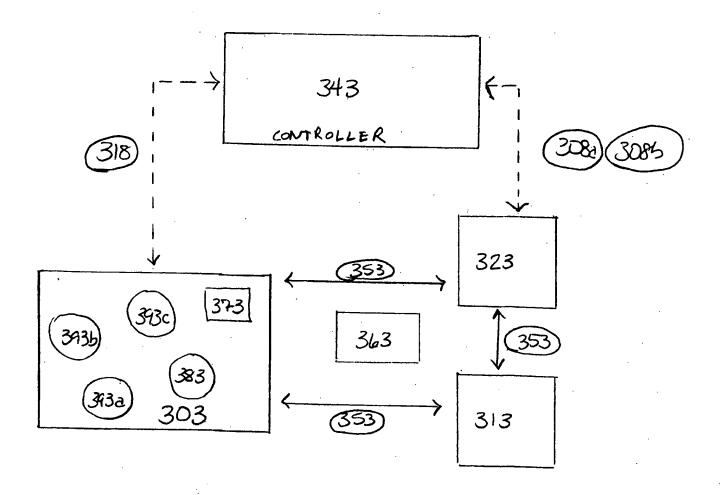
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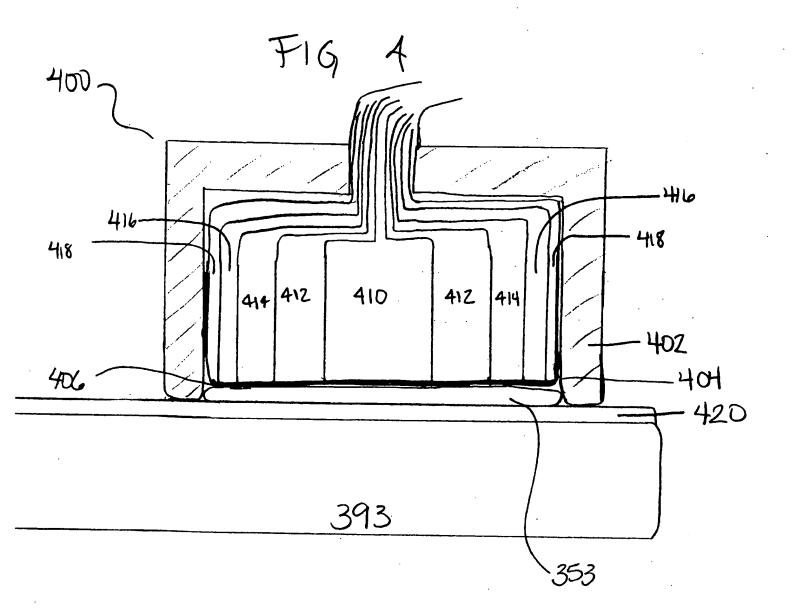




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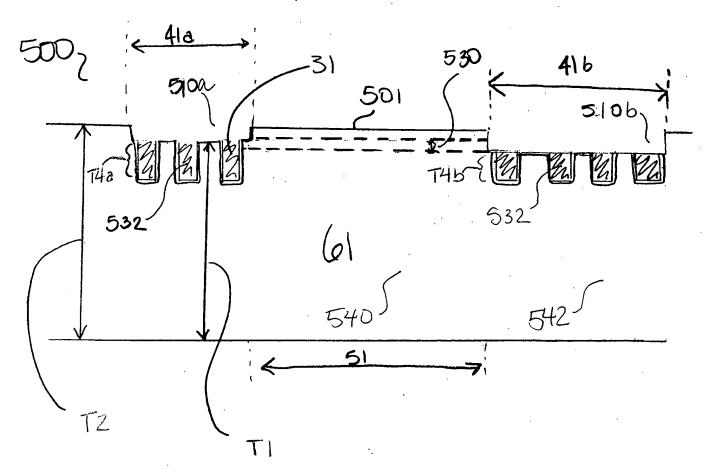


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Fig 5a



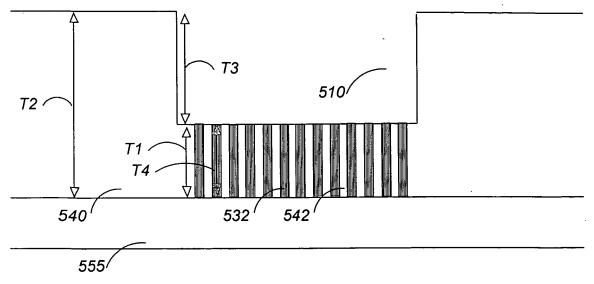


FIG._5b

FIG. 6

POLISH WAFER 602

CLEAN AND DRY WAFER 608

MEASURE THE PROFILE OF THE WAFER WITH AN IN-LINE METROLOGY SYSTEM

SEND THE MEASUREMENTS TO A PROGRAMMABLE CONTROLLER 618

CALCULATE POLISHING PARAMETERS 622

CHANGE POLISHING PARAMETERS USING OUTPUTS CALCULATED BY THE CONTROLLER

POLISH SUBSEQENT WAFER IN THE SEQUENCE (32

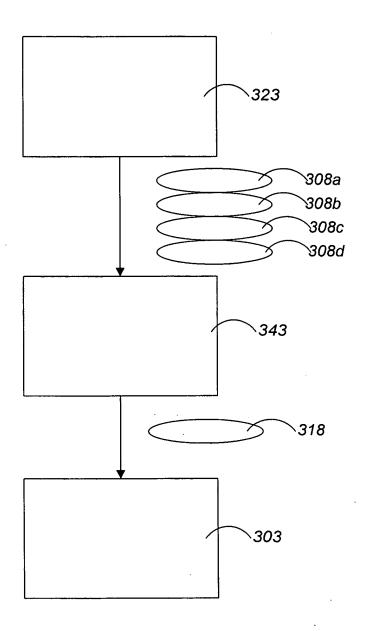


FIG._7